

## UV 减粘膜

### UV Tape

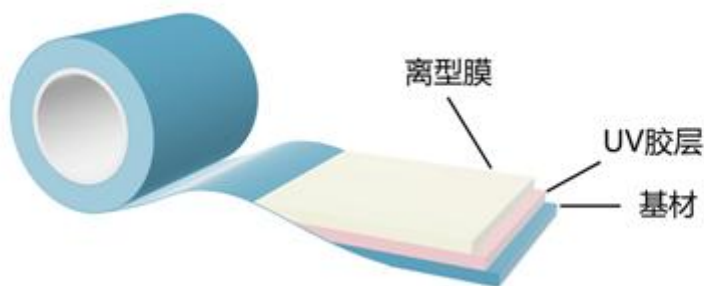
UV 减粘膜是一种特种胶带，其常态下具有很强的粘性，经 UV 光照射后粘性急剧降低，通常用于工件研磨、切割等制程的载带及保护。

UV tape is a special tape, which has excellent adhesiveness under normal conditions. But its adhesiveness decreases rapidly after exposure of UV light. UV tape usually used as carrier tape and protective substrate during the dicing and grinding process.

组成：UV 减粘膜主要由离型膜、UV 胶、基材三部分组成。

UV tape is mainly composed of release film, acrylic adhesive and base film.

UV减粘膜结构



主要特点:

1. UV 照射前具有较高的粘力，能够确保加工过程中工件的稳固；
2. UV 照射后粘力几乎消失，工件易揭离且无残胶、无杂质转移到工件表面；
3. 具有良好的延展性，便于扩膜取粒；
4. 具有一定耐温性，满足特殊温度工艺的使用。

基材 Base film	厚度 ( $\mu\text{m}$ ) Thickness	胶层 Adhesive	胶层厚度 ( $\mu\text{m}$ ) Adhesive thickness	初始粘度 g/25mm Adhesion (before UV)	解胶后 g/25mm Adhesion (after UV)
PO	80、100、140、150	UV 胶水	5 ~ 30	500 ~ 3000	< 20
PET	50、100、188	UV 胶水	5 ~ 30	500 ~ 3000	< 20
注：特殊要求可以定制					

### Main application:

Semiconductor: Dicing of various types of package ( BGA/QFN/DFN ) ,  
wafer sawing and grinding.

Optoelectronics: Slotting, dicing and pickling of coated glass and  
ordinary glass.

Others: Process in which work piece should be covered when machining  
and uncovered after that without adhesive residue.

### 应用领域:

封装领域：各种封装件（ QFN/BGA/DFN ）的切割用；晶圆研磨、切割用。

光学领域：各种镀膜玻璃、普通玻璃的开槽、切割、酸洗用。

其它领域：加工时需要高粘力胶带贴覆，加工后需要将胶带揭离且无残胶。

### Main features:

Excellent adhesiveness before exposed on UV light to ensure work piece  
fixed secure during machining process.

Low adhesiveness after exposed on UV light to make it easier to peel and  
prevent adhesive residue.

High expandability and easy pickup.

High performance to specific process with high temperature.